

BU808DFP

HIGH VOLTAGE FAST-SWITCHING NPN POWER DARLINGTON

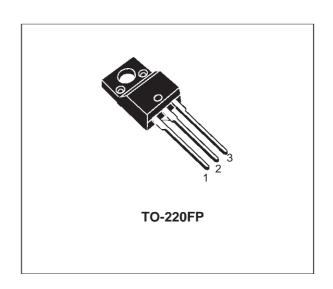
- STMicroelectronics PREFERRED SALESTYPE
- NPN MONOLITHIC DARLINGTON WITH INTEGRATED FREE-WHEELING DIODE
- HIGH VOLTAGE CAPABILITY (> 1400 V)
- HIGH DC CURRENT GAIN (TYP. 150)
- FULLY MOLDED ISOLATED PACKAGE 2KV DC ISOLATION (U.L. COMPLIANT)
- LOW BASE-DRIVE REQUIREMENTS
- DEDICATED APPLICATION NOTE AN1184

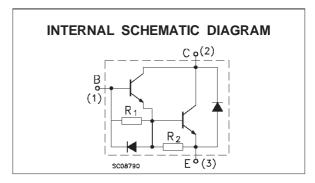
APPLICATIONS

 COST EFFECTIVE SOLUTION FOR HORIZONTAL DEFLECTION IN LOW END TV UP TO 21 INCHES.



The BU808DFP is a NPN transistor in monolithic Darlington configuration. It is manufactured using Multiepitaxial Mesa technology for cost-effective high performance.





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-Base Voltage (I _E = 0)	1400	V
V _{CEO}	Collector-Emitter Voltage (I _B = 0)	700	V
V _{EBO}	Emitter-Base Voltage (I _C = 0)	5	V
Ic	Collector Current	8	А
I _{CM}	Collector Peak Current (t _p < 5 ms)	10	Α
Ι _Β	Base Current	3	А
I _{BM}	Base Peak Current (t _p < 5 ms)	6	А
P _{tot}	Total Dissipation at T _c = 25 °C	42	W
T _{stg}	Storage Temperature	-65 to 150	°C
Tj	Max. Operating Junction Temperature	150	°C

June 2000 1/7

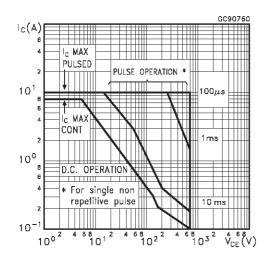
THERMAL DATA

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

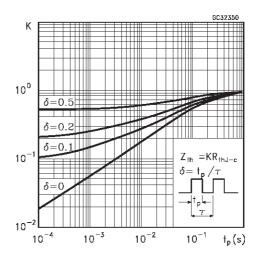
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{CES}	Collector Cut-off Current (V _{BE} = 0)	V _{CE} = 1400 V			400	μΑ
I _{EBO}	Emitter Cut-off Current (I _C = 0)	V _{EB} = 5 V			100	mA
V _{CE(sat)} *	Collector-Emitter Saturation Voltage	$I_C = 5 A$ $I_B = 0.5 A$			1.6	V
V _{BE(sat)*}	Base-Emitter Saturation Voltage	I _C = 5 A I _B = 0.5 A			2.1	V
h _{FE} *	DC Current Gain	$I_{C} = 5 \text{ A}$ $V_{CE} = 5 \text{ V}$ $I_{C} = 5 \text{ A}$ $V_{CE} = 5 \text{ V}$ $T_{j} = 100 ^{\circ}\text{C}$	60 20		230	
t _s	INDUCTIVE LOAD Storage Time Fall Time	$V_{CC} = 150 \text{ V}$ $I_{C} = 5 \text{ A}$ $I_{B1} = 0.5 \text{ A}$ $V_{BEoff} = -5 \text{ V}$			3 0.8	μs μs
t _s	INDUCTIVE LOAD Storage Time Fall Time	$V_{CC} = 150 \text{ V}$ $I_{C} = 5 \text{ A}$ $I_{B1} = 0.5 \text{ A}$ $V_{BEoff} = -5 \text{ V}$ $T_{j} = 100 ^{\circ}\text{C}$		2 0.8		μs μs
V _F	Diode Forward Voltage	I _F = 5 A			3	V

^{*} Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

Safe Operating Area

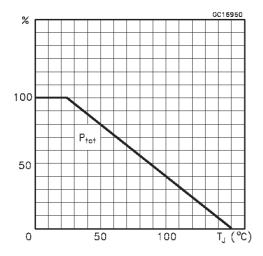


Thermal Impedance

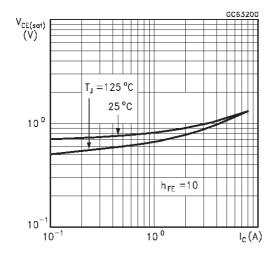


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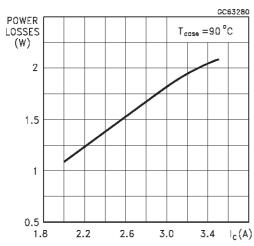
Derating Curve



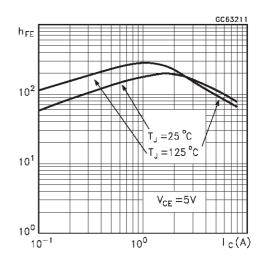
Collector Emitter Saturation Voltage



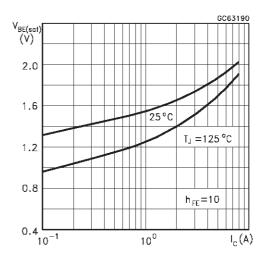
Power Losses at 16 KHz



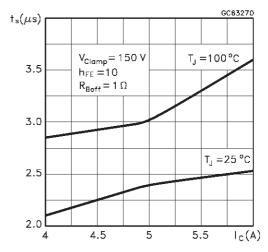
DC Current Gain



Base Emitter Saturation Voltage

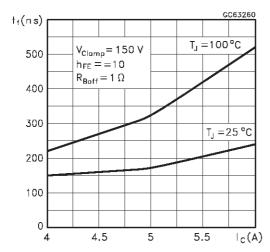


Switching Time Inductive Load at 16KHz



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Switching Time Inductive Load at 16KHZ

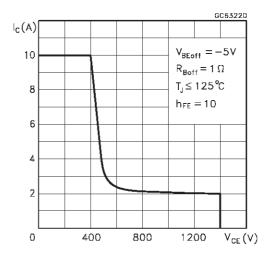


BASE DRIVE INFORMATION

In order to saturate the power switch and reduce conduction losses, adequate direct base current l_{B1} has to be provided for the lowest gain h_{FE} at 100 $^{\circ}$ C (line scan phase). On the other hand, negative base current l_{B2} must be provided to turn off the power transistor (retrace phase).

Most of the dissipation, in the deflection application, occurs at switch-off. Therefore it is essential to determine the value of $I_{\rm B2}$ which minimizes power losses, fall time $t_{\rm f}$ and, consequently, $T_{\rm j}$. A new set of curves have been defined to give total power losses, $t_{\rm s}$ and $t_{\rm f}$ as a function of $I_{\rm B2}$ at both 16 KHz scanning frequencies for choosing the optimum negative

Reverse Biased SOA



drive. The test circuit is illustrated in figure 1.

Inductance L_1 serves to control the slope of the negative base current I_{B2} to recombine the excess carrier in the collector when base current is still present, this would avoid any tailing phenomenon in the collector current.

The values of L and C are calculated from the following equations:

$$\frac{1}{2} L (I_C)^2 = \frac{1}{2} C (V_{CEfly})^2$$
 $\omega = 2 \pi f = \frac{1}{\sqrt{LC}}$

Where I_{C} = operating collector current, V_{CEfly} = flyback voltage, f= frequency of oscillation during retrace.

Figure 1: Inductive Load Switching Test Circuits.

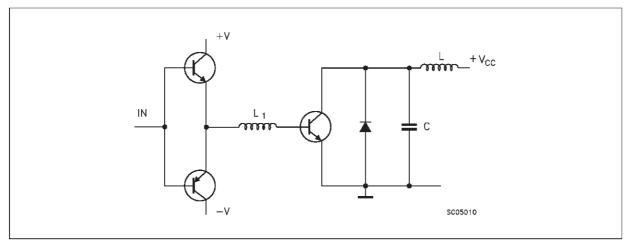
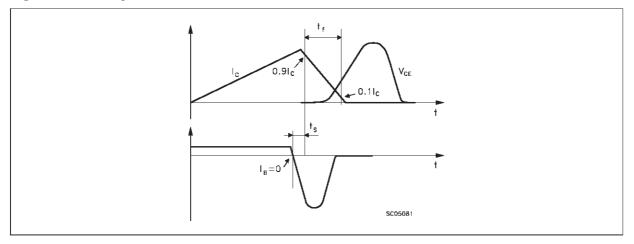
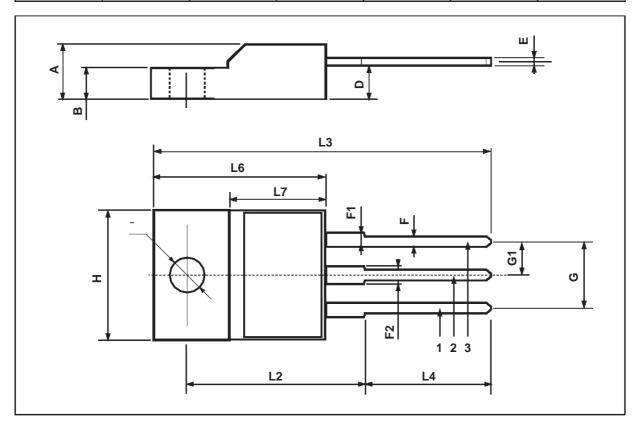


Figure 2: Switching Waveforms in a Deflection Circuit



TO-220FP MECHANICAL DATA

DIM.	mm		inch			
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
Е	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



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